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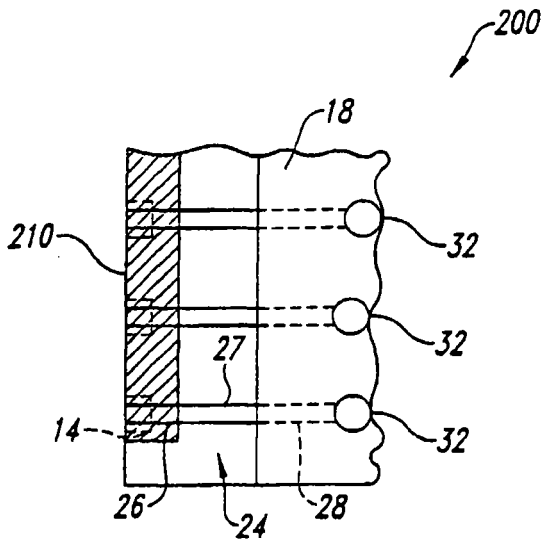
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(54) Title: APPARATUS AND METHODS OF REINFORCEMENT OF LEAD BONDING IN MICROELECTRONIC PACKAGES



(57) Abstract: The present invention is directed toward an apparatus and method for reinforcing of the lead bonding in microelectronic package (10). A microelectronic package (10) includes a microelectronic device (16) having a bond pad (14), a conductive lead having a first end (26) bonded to the bond pad (14) to form a lead bond (24), an encapsulating material (30) disposed about the conductive lead, and a reinforcement portion (110) disposed about the lead bond (24) and coupling the first end (26) to the bond pad (14). The reinforcement portion (110) has a greater modulus of elasticity and/or greater bond strength than the encapsulating material (30).

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